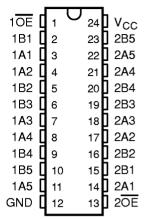
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- Functionally Equivalent to QS3384 and QS3L384
- 5-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)



description

The SN74CBTLV3384 provides ten bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 5-bit bus switches with separate output-enable (\overline{OE}) inputs. It can be used as two 5-bit bus switches or one 10-bit bus switch. When \overline{OE} is low, the associated 5-bit bus switch is on and port A is connected to port B. When \overline{OE} is high, the switch is open, and a high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3384 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each 5-bit bus switch)

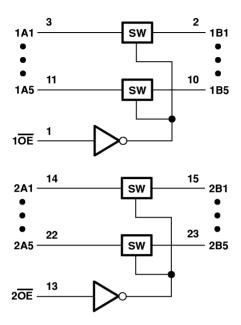
INPUTS		INPUTS/OUTPUTS		
10E	2OE	1B1–1B5	2B1–2B5	
L	L	1A1-1A5	2A1-2A5	
L	Н	1A1-1A5	Z	
Н	L	Z	2A1-2A5	
Н	Н	Z	Z	



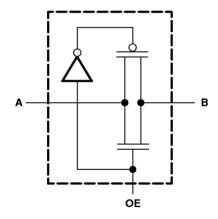
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logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}		
Continuous channel current		
Input clamp current, $I_{IK}(V_{I/O} < 0)$		–50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DBQ package	103°C/W
	DGV package	139°C/W
	DW package	81°C/W
	PW package	120°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage			3.6	٧
VIH	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
	rigit-level control iriput voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
V _{IL}	Low-level control input voltage			0.7	V
	Low-level control input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	
TA	Operating free-air temperature		-4 0	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 3 V,	I _I = -18 mA				-1.2	V
Ц		$V_{CC} = 3.6 \text{ V},$	V _I = V _{CC} or GND				±1	μΑ
l _{off}		$V_{CC} = 0$,	V_{1} or $V_{0} = 0$ to 3.6 V				10	μΑ
Icc		$V_{CC} = 3.6 \text{ V},$	l _O = 0,	V _I = V _{CC} or GND			10	μΑ
∆lcc‡	Control inputs	$V_{CC} = 3.6 \text{ V},$	One input at 3 V,	Other inputs at V _{CC} or GND			300	μΑ
Ci	Control inputs	V _I = 3 V or 0				4.5		pF
C _{io(OF}	F)	$V_O = 3 V \text{ or } 0,$	OE = V _{CC}			10		pF
		V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	$V_{I} = 0$ $V_{I} = 1.7 V,$	I _I = 64 mA		5	8	
				I _I = 24 mA		5	8	Ω
. 8		1111 41 400 = 2:5 4		I _I = 15 mA		27	40	
r _{on} §		V _{CC} = 3 V	V _I = 0	I _I = 64 mA		5	7	
				I _I = 24 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A		0.35		0.25	ns
t _{en}	ŌĒ	A or B	1	5	1	4.3	ns
t _{dis}	ŌE	A or B	1	5.5	1	5.5	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

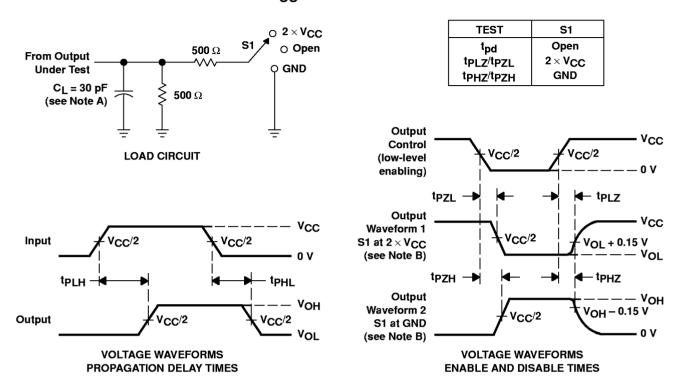


[‡]This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

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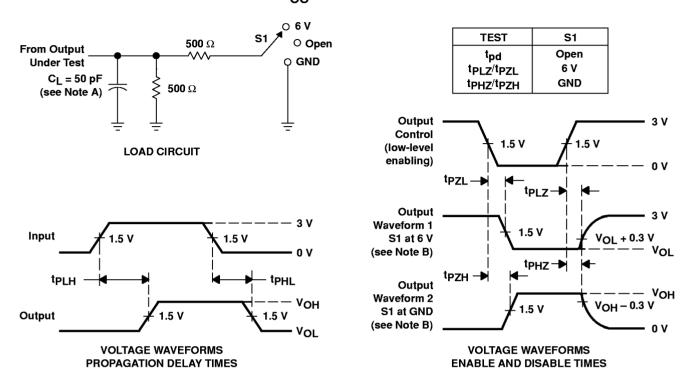
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2 ns. $t_{f} \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \,\Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpl H and tpHI are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

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